

ABSTRACT OF THE DISCLOSURE

A chip package structure is provided. The chip package at least comprises a carrier, a die, a passive component, a plurality of first conducting wires, a second conducting wire, and a dielectric material. Two electrodes of the passive component
5 are electrically connected to the power pad and the ground pad, respectively. Since one end of the conducting wire is directly connected to one electrode of the passive component, the length of the conducting wire can be effectively shortened. Hence the signal transmission path is shorter and there is more layout space for conducting wires.